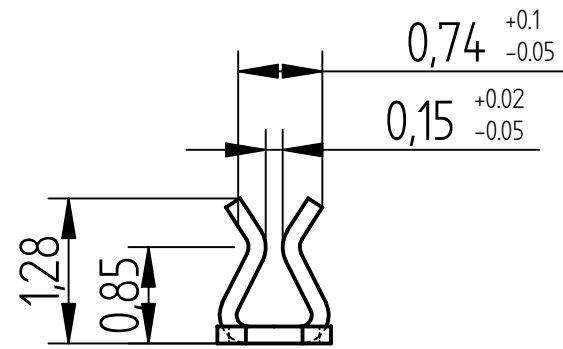
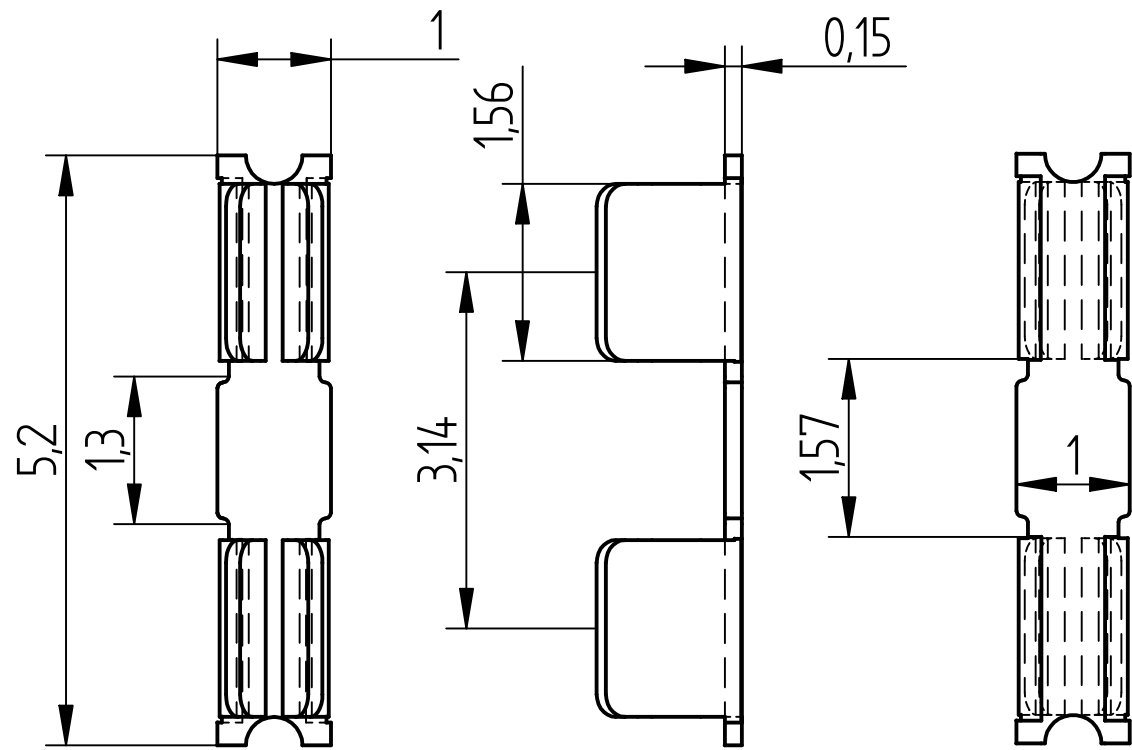
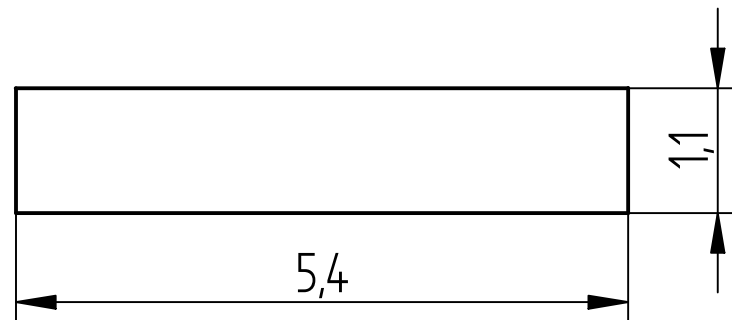


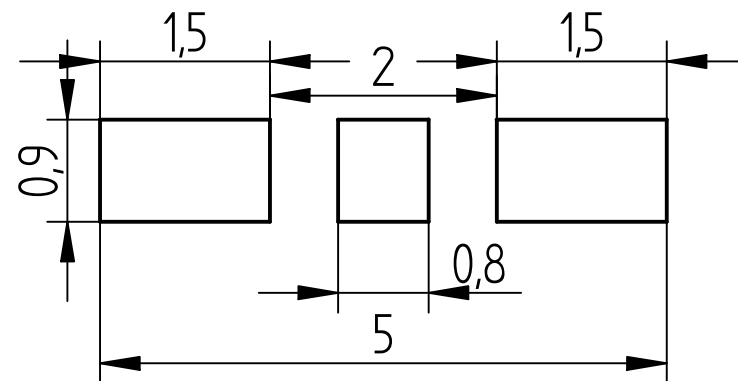
REVISION HISTORY			
REV	DESCRIPTION	DATE	APPROVED
A	신규제정	2009.04.05	P.K.KO
B	BOTTOM면 R변경 0.1 R	2010.08.23	P.K.KO
C	인입부 공차 변경 0.74 +0.1 -0.05	2012.02.17	P.K.KOH
D	SHIELD CASE THICKNESS 0.2 ±0.02 ⇒ 0.2 +0.02 -0	2012.03.30	P.K.KOH



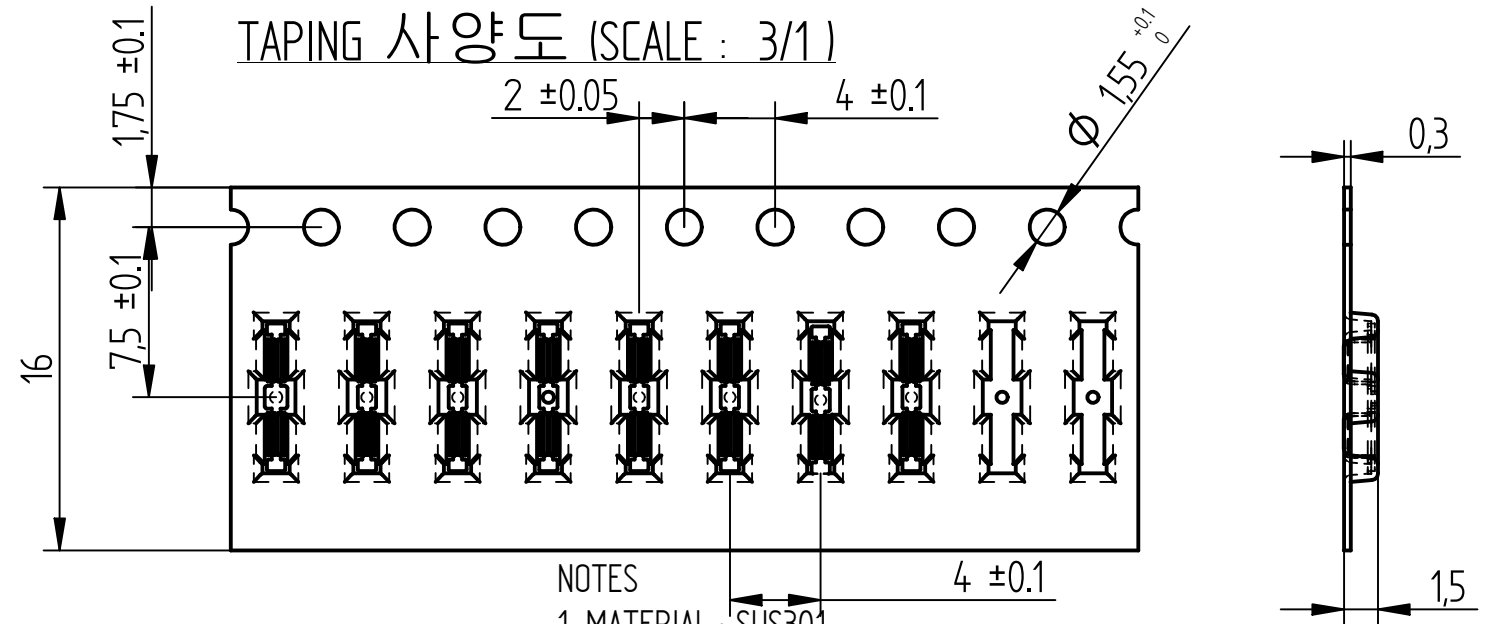
SCALE 15 / 1



RECOMMENDED PCB LAYOUT



RECOMMENDED STENCIL LAY-OUT 0.1T



NOTES

1. MATERIAL : SUS301
2. MATERIAL THICKNESS : 0.15t
3. FINISHED : Sn(100%) PLATING ON BOTH SIDE
(Ni0.5 μ m Sn1.27 μ m)
4. PACKING MATERIALS.
- REEL : HIPS 0.3t
- COVER TAPE : PS
- Q'TY/REEL : 10,000ea
5. AVAILABLE SHIELD CASE THICKNESS : 0.2 +0.02 -0
6. CONTACT RESISTANCE 300mm Ω MAX
7. INTENTION FORCE/RETENTION FORCE SPEC

	INTENTION FORCE	RETENTION FORCE
SPEC	MAX 1.6Kg	MIN 0.5Kg

8. STENCIL THICKNESS : 0.12T
9. Maintain 90°±3 while engage & disengage shield can & shield clip to prevent deformation & to maintain retention force of shield clip

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE
ANGLES ± 0.3°
0 ~ 1 ± 0.05
1 ~ 5 ± 0.1
5 ~ 10 ± 0.15

INNOCHIPS TECHNOLOGY
ICT (주)이노칩테크놀로지
Solution Provider

TITLE SHILED CLIP		
SIZE A3	DWG NO ICSRC-5210SFR	REV D
FILE NAME: ICSRC-5210SFRdft.dft		
SCALE:	WEIGHT:	SHEET 1 OF 1